

Pelnox®

Product Name	ME-281/HV-141
Product Category	Potting Resin for Semiconductors, Resin for Car Electro Devices & Sensors
Usage	Semiconductor Modules, Car Electro Devices, Sensors, Relays
Function	Heat Resistant, High Tg, Heat Cycle Resistant, Moisture Resistant

As supplied

(Typical Value)

Item	Condition	Unit	ME-281	HV-141
Appearance	visual	–	Black liquid	White liquid
Specific Gravity	25°C	–	1.87	1.83
Viscosity	25°C	mPa·s	28,000	15,000
Mixing Ratio	parts by weight		100/100	
Mixed Viscosity	25°C	mPa.s	10,000	
Pot Life	25°C	hour	>5	
	40°C	hour	4	
	50°C	hour	2.5	
Gel Time	100°C 40g	miute	40	

Standard Curing Condition **100°C x 1 hour + 200°C x 1 hours**

As cured

Item	Condition	Unit	Typical Value
Hardness	JIS K-7215 25°C	Shore D	96
Glass Transition Temperature	TMA	°C	209
Coefficient of Thermal Expansion	below Tg	10 ⁻⁵ /°C	1.5
	above Tg	10 ⁻⁵ /°C	5.8
Flexural Strength	JIS K-6911 25°C size:10×120×4mm	MPa	115
Flexural Modulus	JIS K-6911 25°C size:10×120×4mm	MPa	14,500
Shear Adhesive Strength	JIS K-6850 25°C (Ni-Ni)	MPa	13
Cure Shrinkage		%	0.11
Volume Resistivity	JIS K-6911 25°C	Ω-cm	2.5 x 10 ¹⁶
	JIS K-6911 boil for 2hrs	Ω-cm	4.2 x 10 ¹⁵
Water Absorption	JIS K-6911 boil for 2hrs	wt%	0.11
	JIS K-6911 boil for 24hrs	wt%	0.52
Thermal Conductivity	Quick Thermal Conductivity Meter	W/mK	0.7

The above values are typical and not specification



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